Reinforced, Isolated, Phase-Current Sense Reference Design With Small Delta-Sigma Modulators

Description
The TIDA-00914 design realizes a reinforced, isolated, three-phase inverter subsystem using isolated-IGBT gate drivers and isolated current and voltage sensors. Precise, in-line, shunt-based, motor-phase current sensing is done with AMC1306E25 delta-sigma ($\Delta\Sigma$) modulators. The modulator output is Manchester encoded, which simplifies the clock and data signal routing between the MCU and modulators. The high CMTI of the modulator helps suppress inverter switching transients from corrupting the data on the controller side. The small size of the modulator enables a compact solution. The TIDA-00914 provides an interface to connect to an external MCU or FPGA where digital SINC filters can be implemented to demodulate the AMC1306E25 output bit stream. This TI Design uses the F28379D Delfino™ control card, which is connected to the TIDA-00914 card through an adapter card to implement SINC filters for current sensing.

Resources
- TIDA-00914 Design Folder
- AMC1306E25 Product Folder
- UCC5310MCDWV Product Folder
- UCC5320SCDWV Product Folder
- UCC5390ECDWV Product Folder
- LM3480 Product Folder
- TLV704 Product Folder
- TLV1117-33 Product Folder
- SN74LVC1G17 Product Folder
- TMDSNCD28379D Tool Folder

Features
- Reinforced Isolated Inverter Power Stage Suited for 200- to 480-V AC Powered Drives
- Reinforced Isolated $\Delta\Sigma$ Modulator With Manchester Encoded Output to Measure In-Line Motor Phase Current With Shunt Resistor
- Simplified Clock Routing to $\Delta\Sigma$ Modulators due to Manchester Encoded Data Output; Enables Daisy Chaining of Clock Signals
- Small Pin Count (8) Enables Compact Solution
- High CMTI of Modulator (> 50 kV/µs) Improves Noise Immunity to Switching Transients
- Short-Circuit Response Time of < 1.5 µs With SINC 3 Filter and OSR 8
- Nominal Phase Current Measurement Range of 28 A$_{RMS}$, Transient Peak Range of ±80 Apk With 4-mΩ Shunt Resistor
- Calibrated Full-Scale Error of < 0.5 % Across Temperature Range of 0°C to 55°C
- Allows for Isolated Measurement of DC-Link Voltage With $\Delta\Sigma$ Modulator
- Allows for Isolated Measurement of IGBT Power Module Temperature Using NTC Integrated in Module With $\Delta\Sigma$ Modulator

Applications
- AC Inverter and VF Drives
- Servo Drives and Motion Control
1 System Description

High-resolution, accurate, isolated phase current measurement is vital in industrial motor drive applications where high-performance torque and motion control are required. These applications include servo drives, robotics, machine tools, industrial manufacturing, and CNC machines. The options available for phase current measurement are to use Hall effect sensors, flux gate sensors, current transformers, or shunt resistors. The first three options have inherent galvanic isolation benefits and a high current measurement range, but the linearity, bandwidth, and drift are of lower performance when compared to the shunt resistor option. When the maximum continuous current to be measured is less than 50 A, then using shunt resistors provides a highly linear, high-bandwidth, cost-effective measurement solution.

Isolated shunt-based current measurement can be done either by using an isolated amplifier or an isolated delta-sigma ($\Delta\Sigma$) modulator. The amplifier-based solution has three conversion stages consisting of an isolated amplifier, a differential-to-single-ended amplifier with a filter, and a SAR ADC. Each stage adds error and achieves an accuracy of < 10 bits on the system level. For a higher resolution analog signal chain, the cost increases exponentially. Short-circuit detection using isolation amplifiers require additional circuitry, which consist of window comparators and reference generators for setting short-circuit thresholds. The short-circuit detection delay is higher in this case because of the propagation delays of the amplifier plus the comparator. The $\Delta\Sigma$ modulator-based solution has a single conversion stage, and most of the processing is done in the digital domain, which makes it less susceptible to noise in the system and it is possible to get accuracy of > 14 bits at the system level.

As shown in Figure 1, there are two paths implemented in the sigma-delta ($\Sigma\Delta$) filter module (SDFM) to demodulate data. One is a high-resolution, precise data filter unit. This unit has a configurable SINC filter and high oversampling ratio (OSR), preferably SINC 3 and OSR of > 64. The output of the filter unit is stored in data registers and used for position and torque control. The output of this filter is not preferred for drive protection because of the high latency of the path. The second path is a low-latency, lower resolution overcurrent sense comparator path. This unit also has configurable SINC filter and OSR. The OSR is usually limited to much lower range, which enables low latency. The output of the filter is passed through a digital window comparator with programmable thresholds. The comparator output is used to trip the PWM signals in case of short circuit. It is possible to achieve a response time of < 1.5 µs with a SINC 3 filter and OSR of 8.

![Figure 1. $\Sigma\Delta$ Modulators in Motor Drives](image-url)
Different clock and data line lengths may cause propagation delay mismatch between the two signals. A delay mismatch may cause setup and hold time issues at the microcontroller (MCU). Avoiding this issue requires careful layout routing and signal length matching. The clock signal termination is more problematic. This setup and hold time issue can be solved by Manchester encoding the data signal. An Manchester encoded bit stream is shown in Figure 2. In this coding scheme, the clock is embedded into the data stream, which enables easier routing of clock and data signals reducing wiring efforts. Clock termination is much easier as the clock signal can be daisy chained between multiple modulators.

![Manchester Encoded Data](image)

Figure 2. Manchester Encoded Data

This reference design consists of a 3φ power stage using TI’s wide body package (DWV) small (8-pin) reinforced isolated ΔΣ modulator AMC1306E25 for in-line phase current sensing and is intended to drive motors for various industrial applications. The AMC1306E25 uses IEEE 802.3 compliant Manchester encoding. This TI Design demonstrates the following in a real system:

- Loss of hi-side power detection
- Modulator input overrange detection
- Short-circuit detection and response time
- Current measurement accuracy

### 1.1 Key System Specifications

<table>
<thead>
<tr>
<th>SUBSECTION</th>
<th>PARAMETER</th>
<th>SPECIFICATIONS</th>
<th>COMMENT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Inverter</td>
<td>DC bus input voltage</td>
<td>200- to 900-V DC</td>
<td>Up to 1200-V DC absolute maximum by changing connectors and fuse</td>
</tr>
<tr>
<td></td>
<td>Output frequency</td>
<td>0 to 100 Hz</td>
<td>—</td>
</tr>
<tr>
<td></td>
<td>PWM switching frequency</td>
<td>2 to 16 kHz</td>
<td>—</td>
</tr>
<tr>
<td></td>
<td>PWM dead band</td>
<td>1 µs</td>
<td>Inverter tested with 1-µs deadband; can be varied as long as there is no overlap between VGE signals of top and bottom IGBT switches</td>
</tr>
<tr>
<td></td>
<td>Power switch used</td>
<td>1200-V, 100-A six-pack inverter IGBT module</td>
<td>Part number: CM100TX-24S</td>
</tr>
</tbody>
</table>
### Table 1. Key System Specifications (continued)

<table>
<thead>
<tr>
<th>SUBSECTION</th>
<th>PARAMETER</th>
<th>SPECIFICATIONS</th>
<th>COMMENT</th>
</tr>
</thead>
<tbody>
<tr>
<td>Current sensing</td>
<td>Continuous motor phase current</td>
<td>28 A&lt;sub&gt;RMS&lt;/sub&gt; (40 A&lt;sub&gt;PK&lt;/sub&gt;) per phase maximum.</td>
<td>Can be increased to 44 A&lt;sub&gt;RMS&lt;/sub&gt; max by changing DC bus input and motor power connectors, fuse, and using appropriate heat sinking</td>
</tr>
<tr>
<td></td>
<td>Transient overload maximum</td>
<td>80 A&lt;sub&gt;PK&lt;/sub&gt; with 4-mΩ shunt resistor</td>
<td>—</td>
</tr>
<tr>
<td></td>
<td>Phase current measurement error</td>
<td>&lt; 0.5% calibrated</td>
<td>—</td>
</tr>
<tr>
<td></td>
<td>Maximum modulator clock frequency</td>
<td>20 MHz</td>
<td>—</td>
</tr>
<tr>
<td></td>
<td>Logic Interface</td>
<td>3.3-V CMOS logic with Schmitt trigger</td>
<td>—</td>
</tr>
<tr>
<td>Feedback</td>
<td>Measured variables</td>
<td>2 phase currents, module temperature, DC-link voltage</td>
<td>Feedbacks required for motor control and protection</td>
</tr>
<tr>
<td></td>
<td>Phase current</td>
<td>Inverter shutdown on overload</td>
<td>User software implementation</td>
</tr>
<tr>
<td></td>
<td>DC bus voltage</td>
<td>Overvoltage and undervoltage detection</td>
<td>User software implementation</td>
</tr>
<tr>
<td></td>
<td>Current sensor</td>
<td>Holds output data constant when hi-side power is lost.</td>
<td>Indication to the controller that data is no longer valid</td>
</tr>
<tr>
<td></td>
<td></td>
<td>Toggles every 128 bits when common-mode input voltage range of sensor is violated</td>
<td></td>
</tr>
<tr>
<td></td>
<td>Module temperature</td>
<td>Overtemperature shutdown</td>
<td>User software implementation</td>
</tr>
<tr>
<td></td>
<td>Isolation</td>
<td>Reinforced isolated</td>
<td>Reinforced isolated current sensor and gate drivers used; 8.89-mm spacing between primary and secondary side</td>
</tr>
<tr>
<td>Operating conditions</td>
<td>Temperature range</td>
<td>0°C to 55°C</td>
<td>Components selected support the industrial temperature range of 85°C and the TIDA can operate outside the mentioned temperature range with sufficient derating. Tested only from 0°C to 55°C</td>
</tr>
<tr>
<td></td>
<td>Microcontroller interface</td>
<td>7 PWM signals, current sense modulator bit streams for two motor phases, DC-link voltage sense modulator bit stream, temperature sense modulator bit stream, clock signal, 5 V for the controller board</td>
<td>See Table 5 for pin assignment</td>
</tr>
<tr>
<td>Interface connectors</td>
<td>Primary side power</td>
<td>5 V ± 5%, 500 mA</td>
<td>For powering primary side of gate drivers, modulators, and the controller card</td>
</tr>
<tr>
<td></td>
<td>Secondary side power</td>
<td>15 V ± 5%, 200 mA</td>
<td>For powering the secondary side of gate drivers and LDOs, which generate 5 V for the current sense modulators and 3.3 V for the DC bus voltage sense and temperature sense modulators</td>
</tr>
<tr>
<td>PCB Information</td>
<td>PCB layer stack</td>
<td>4 layer, 1-oz copper</td>
<td>35-micron copper</td>
</tr>
<tr>
<td></td>
<td>Laminate</td>
<td>FR4, high Tg</td>
<td>—</td>
</tr>
<tr>
<td></td>
<td>PCB thickness</td>
<td>1.6 mm</td>
<td>—</td>
</tr>
<tr>
<td></td>
<td>PCB size</td>
<td>167 mm × 178 mm</td>
<td>—</td>
</tr>
</tbody>
</table>
2 System Overview

2.1 Block Diagram

Figure 3 shows the system block diagram of the reinforced isolated three-phase inverter with in-line precision phase current sensing with a shunt resistor. The TIDA-00914 design is highlighted with a red dashed box.

The inverter section is composed of a six-pack IGBT module that contains three half bridges. Each IGBT of the module is driven by a reinforced, isolated-gate driver, UCC5310MCDWV. A unipolar 15-V power supply is used for driving the IGBT gates. The PWM input signals for the gate drivers are routed to a D-SUB 25-pin female connector, which is connected to the Delfino control card TMDSCNC828379D through an adapter board. For more information on gate-driver design using UCC53x0 devices, see the TIDA-01420 reference design, which uses the basic isolated version of the gate driver.
The inverter power stage is designed to be protected against short circuits, DC bus under- and overvoltage, and IGBT module overtemperature. DC bus voltage is sensed with a voltage divider. The scaled voltage is sensed with the AMC1306E25. DC bus under- and overvoltage thresholds are set inside software. To monitor IGBT module temperature, a voltage divider is formed with an external resistor and the NTC integrated inside the module. The voltage drop across the NTC is sensed by the AMC1306E25 device. Because the resistance of the NTC and the input impedance of the AMC1306 device are comparable, an op-amp voltage follower buffer is inserted between the NTC and AMC1306 input stage to reduce error in temperature measurement. The op-amp buffer used is the cost-optimized TLV521. The actual temperature is derived from the voltage across NTC by software implemented in the controller.

In-line motor phase current sensing is done by inserting a shunt resistor between the phase output of the inverter and the phase terminals of the motor. The voltage drop across the shunt resistor is sensed by an AMC1306 device. The transfer function of the current sense signal chain path is used to derive the phase current values in the controller. The bit stream of the ΔΣ modulators are Manchester encoded; decoding of the data must be done before filtering it. Manchester encoding makes clock and data signal routing between the controller and the modulator much easier. A configurable digital SINC filter is implemented inside the controller to decimate the bit stream from the ΔΣ modulators. The short-circuit threshold value is set within software. The clock is routed to the PCB D-SUB 25-pin connector from the controller card through ribbon cable. A clock buffer is implemented on the PCB using SN74LVC1G17 Schmitt trigger buffer. The clock signal from the buffer is routed to each AMC1306 device by daisy chaining. In this TI Design, characterization the Manchester decoding and SINC filters are implemented within dedicated ΣΔ filter modules (SDFM) present within the TMS320F28379D.

A primary-side 3.3-V power supply is derived from the 5-V input with the LDO regulator TLV1117-33I. This 3.3 V is supplied to the primary side of the ΔΣ modulators, the gate drivers, and the clock buffer. A secondary-side 3.3-V power supply is generated from the secondary-side 15-V low-side gate driver power supply with the LDO regulator TLV70433. This supply powers the secondary side of the DC bus sensing and temperature sensing ΔΣ modulators and the TLV521 buffer. Secondary-side 5-V power supplies for the phase current sense ΔΣ modulators are derived from the corresponding 15-V secondary high-side gate driver power supplies using the LM3480IM3-5.0 LDO. The high-side gate drive power supplies are generated by bootstrapping the 15-V low-side gate driver power supply.

NOTE: It is also possible to evaluate the split-output version (UCC5320SCDWV) and the bipolar-supply version (UCC5390ECDWV) with this reference design. The schematic file available on the TIDA-00914 product page shows the component changes needed.

### 2.2 Highlighted Products

#### 2.2.1 AMC1306E25

The device is a precision, ΔΣ modulator with the output separated from the input circuitry by a capacitive double isolation barrier that is highly resistant to magnetic interference. Used in conjunction with isolated power supplies, the device prevents noise currents on a high common-mode voltage line from entering the local system ground and interfering with or damaging low voltage circuitry. The input of the AMC1306 is optimized for direct connection to shunt resistors or other low-voltage level signal sources. The output bit stream of the AMC1306Ex is Manchester encoded. By using an appropriate digital filter to decimate the bit stream, the device can achieve 16 bits of resolution with a dynamic range of 85 dB at a rate of 78 kSPS. The small pin count (8 pins) of the modulator helps achieve a compact current sense solution.
2.2.2 **LM3480**

This device is an integrated linear voltage regulator. It features operation from an input as high as 30 V and an ensured maximum dropout of 1.2 V at the full 100-mA load. A standard package for the device is SOT-23. The small package size and wide input range of this device makes it suitable to generate a 5-V floating power supply for the current sense ICs from the 15-V floating supply used to power up the high-side gate drivers.

![Functional Block Diagram of LM3480](image-url)
2.2.3 TLV704

This device is a low dropout regulator with ultra-low quiescent current requirement. The TLV704 operates over a wide operating input voltage range of 2.5 to 24 V, making it ideal for generating a secondary-side 3.3-V power supply from the 15-V low-side gate driver power supply. The device is an excellent choice for industrial applications that undergo large line transients.

![Functional Block Diagram of TLV704](image)

Figure 6. Functional Block Diagram of TLV704

2.2.4 TLV1117

This device is a positive low-dropout voltage regulator designed to provide up to 800 mA of output current. Dropout voltage is specified at a maximum of 1.3 V at 800 mA, decreasing at lower load currents. The device is used to generate a primary-side 3.3-V power supply from the 5-V input.

![Functional Block Diagram of TLV1117](image)

Figure 7. Functional Block Diagram of TLV1117

2.2.5 SN74LVC1G17

This device is a single Schmitt-trigger buffer designed for 1.65- to 5.5-V $V_{CC}$ operation. The SN74LVC1G17 contains one buffer and performs the Boolean function $Y = A$. The CMOS device has a high output drive of 24 mA at 3.3 V while maintaining low static power dissipation over a broad $V_{CC}$ operating range. The device is used to buffer the clock signal coming from the MCU into the PCB.
2.2.6 UCC5310MCDWV

The UCC53x0 family of devices are single-channel, isolated gate drivers, with variants for pinout configuration and drive strength. The UCC5310M variant is used in this design. This device connects the gate of the transistor to an internal clamp, to prevent false turnon caused by miller current. The SOIC-8 DWV (wide-body) package is used, which supports an isolation voltage up to 5 kVrms. This device has 2.4-A minimum source capability and 1.1-A minimum sink capability. Compared to the optocoupler, the UCC53x0 has lower part-to-part skew, lower propagation delay, higher operating temperature, and higher CMTI.

![Figure 8. Functional Block Diagram of UCC5310MCDWV](image)
3 System Design Theory

3.1 DC to Three-Phase AC Inverter Subsystem

A six-pack IGBT module CM100TX-24S is used to convert input DC bus voltage into 3φ AC for driving the induction motor. Each of the six IGBT power switches are controlled by reinforced isolated gate drivers using unipolar 15-V gate-to-emitter voltages. R20, R32, R112, R12, R38, and R26 are 10-kΩ resistors used to ensure that the IGBTs remain off in case the gate drivers get disconnected due to system malfunction. C72 to C77 are provisions for additional external gate-to-emitter capacitance. R118 and R120 are shunt resistors used for U and W phase current sensing.

Terminal block J8 is the DC bus voltage input connector. C112 and C111 are localized high-frequency DC bus decoupling capacitors. This TI Design uses 3-µF, 1300-V film capacitors. XF2 and XF1 are fuse holders. A 30-A, 1-kV DC cartridge fuse of dimension 10.3 mm x 38 mm has to be placed within the fuse holders. Once the DC bus voltage is powered off, some time is needed for the DC bus link capacitors to discharge. This creates a safety hazard. Therefore, bleeder resistors R45, R48, R49, R50, R51, R54, and R57 are added across the DC link. These resistors ensure quick discharge of the DC bus capacitors on power off. Provision is given to connect brake resistor to the DC bus. In case of motor regeneration, if the DC bus voltage goes above a specified threshold, the brake chopper can be initiated. J3 is the terminal block used to connect the braking resistor. D9 is the freewheeling diode connected across the braking resistor to prevent overshoots at the collector of brake chopping IGBT power switch Q1.

The inverter stage is designed to drive induction motors up to 11 kW. Table 2 shows the specifications of a sample 11-kW induction motor:

![Figure 9. Schematic of DC to Three-Phase AC Inverter](https://www.ti.com/lit/ds/symlink/tidud07a.pdf)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>SPECIFICATION</th>
</tr>
</thead>
<tbody>
<tr>
<td>Part number</td>
<td>M2BAX 160MLA</td>
</tr>
<tr>
<td>Output power</td>
<td>11 kW</td>
</tr>
<tr>
<td>International efficiency class</td>
<td>IE2</td>
</tr>
<tr>
<td>Motor efficiency</td>
<td>89.8%</td>
</tr>
<tr>
<td>Power factor</td>
<td>0.79</td>
</tr>
<tr>
<td>Poles</td>
<td>4</td>
</tr>
<tr>
<td>Speed</td>
<td>1500 rpm</td>
</tr>
<tr>
<td>Frequency</td>
<td>50 Hz</td>
</tr>
<tr>
<td>Line-to-line voltage</td>
<td>400 V&lt;sub&gt;rms&lt;/sub&gt;</td>
</tr>
</tbody>
</table>
The inverter output power required is calculated in Equation 1, and the maximum inverter output current taking a 15% tolerance on the minimum grid voltage is calculated in Equation 2:

\[
\text{Inverter output power} = \frac{\text{Motor shaft power}}{\text{Efficiency of motor}} = \frac{11000}{0.898} = 12.249 \text{ kW}
\]

\[
\text{Maximum inverter output current} = \frac{\text{Inverter output power}}{\sqrt{3} \times \text{PF} \times \text{Minimum motor input voltage}}
\]

\[
\text{Maximum inverter output current} = \frac{12249}{\sqrt{3} \times 0.79 \times (380 - (0.15 \times 380))} = 27.71 \text{ A}_{\text{RMS}}
\]

### 3.2 In-Line Phase Current Sensing

Accurate, linear motor phase current feedback is very important for an accurate position and torque control of the motor. Phase current information is also required to detect short circuits. In this TI Design, shunt-based in-line phase current sensing is done. Shunt-based current sensing provides the benefits of being highly accurate, linear, smallest form factor, and low cost when compared to Hall sensors or current transformers. The only disadvantage being higher power loss in the shunt resistors at higher currents and the resulting temperature drift. Shunt-based current sensing is ideal if the maximum continuous current to be measured is less than around 50 A. The AMC1306E25 ΔΣ modulators are used for isolated reading of the voltage drop across the shunt resistors. The exact phase current can be computed in software by multiplying the voltage across the shunt resistors by a scaling factor. The current sense scheme for measuring U phase current is shown in Figure 10. The current sensing for the W phase is similar.

As mentioned in Section 3.1, the maximum continuous current to be measured is \( \approx 28 \text{ A}_{\text{RMS}} \), which leads to a peak current of 40 \( \text{A}_{\text{PK}} \). A 4-mΩ shunt resistor is used in this TI Design. The transfer function for the current sensor is shown in Equation 3:

\[
V_{R120} = I_{\text{U \text{--Phase}}} \times R120 = 0.004I_{\text{U \text{--Phase}}}
\]

A peak current rating of \( \pm 40 \text{ A}_{\text{PK}} \) results in a \( \pm 0.16 \)-V drop across the shunt resistor R120 and a maximum power dissipation of 3.2 W. A 7 W, a 1%, \( \pm 75 \text{ ppm} / ^\circ \text{C} \) resistor in the 5931 package is selected. The AMC1306E25 has a high-linearity input voltage range of \( \pm 250 \text{ mV} \) and clips at \( \pm 320 \text{ mV} \). This enables short-term overload current measurement of 1.5 times the maximum continuous current and short-circuit measurement up to 80 \( \text{A}_{\text{PK}} \).

C85 and C89 are noise decoupling capacitors on the high-side power supply, and C62 and C66 are noise decoupling capacitors on the low-side power supply. R47 and R46 are termination resistors on the high-frequency data and clock digital signals. The high-side of the AMC1306 is powered from the high-side gate driver power supply of U Phase through LDO U22. The LDO LM3480 is available in a SOT23 package, which enables a very compact solution. The primary-side operating current of the AMC1306 is 9.8 mA (maximum). This leads to a maximum power dissipation of 98 mW across the LDO. The maximum junction temperature of the LDO at 55°C ambient will be \( \approx 80^\circ \text{C} \).
The data output of the AMC1306E25 is Manchester encoded and connected to the Delfino controller TMS320F28379D. The controller SDFM peripheral decodes the Manchester data. The decoded data is simultaneously passed through two paths. One path is a high-OSR, SINC 3 filter path with high accuracy and latency suitable for motor position and torque control. The other path is a low-OSR path with low accuracy and latency suitable for short-circuit detection. It is recommended to use a 128-OSR, SINC 3 filter for motor phase current sensing and an 8-OSR, SINC 3 filter for short-circuit detection.

3.3 DC-Link Voltage Sensing

DC-link voltage feedback is required for under- and overvoltage protection as well as maintaining constant power delivery to the motor even with DC bus voltage tolerances. A high-impedance resistive voltage divider is implemented using R98, R108, R122, R125, R127, R128, R129, and R109 as shown in Figure 11. The voltage across R109 is read by the $\Delta \Sigma$ modulator, which has to be scaled in software to get the exact DC bus voltage. 0- to 1200-V DC is read as 0- to 0.209-V DC by the AMC1306 as calculated in Equation 4. R107 equaling to R109 has to be added to cancel out errors due to the AMC1306 input bias current flowing through R109.

$$V_{\text{DCSense}} = V_{\text{DCBUS}} \times \frac{R109}{(R98 + R108 + R122 + R125 + R127 + R128 + R129) + R109}$$

$$V_{\text{DCSense}} = 1200 \times \frac{1000}{(820000 \times 7) + 1000} = 1200 \times 0.1742 \text{ m} = 0.209 \text{ V}$$

Figure 11. Schematic of DC-Link Voltage Sensing
A differential input filter can be implemented using R83, R82, and C81. This TI Design does not use this filter; R83 and R82 are equal to 0 Ω and C81 is DNP. The feedback from the voltage divider is unidirectional whereas the input of the AMC1306 can read bidirectional voltages. The complete input voltage range of the AMC1306 can be used by level shifting the negative input of the device to 0.250 V. In this TI Design, R81, R107, and C94 give a provision for level shifting. D10 and D11 are Zener diodes, which are unpopulated. By using these diodes, the input range of the AMC1306 can correspond from 400 to 1200 V instead of 0 to 1200 V. This feature is useful if there is no necessity to measure DC-link voltage below 400 V. C64 and C82 are noise decoupling capacitors for the secondary-side power supply whereas C62 and C58 are for the primary side. R56 and R55 are series line terminating resistors for the data line and clock input.

3.4 IGBT Power Module Temperature Sensing

Temperature feedback of the IGBT power module is necessary for overtemperature shutdown as well as derating the output of the inverter at higher temperatures. Module temperature is measured using the NTC integrated inside the module. The NTC thermal characteristics are shown in Figure 12:

![Figure 12. Temperature Characteristics of NTC Thermistor](image-url)
A resistor divider is formed using R106 and the NTC resistor as shown in Figure 13. The voltage across the NTC resistor is read by the AMC1306. The exact temperature can be calculated in software using Equation 5 and Equation 6.

\[ R_{\text{NTC}}(T) = R_{106} \times \frac{\text{AMC reading}}{3.3 - \text{AMC reading}} \]

\[ T = \frac{1}{\ln \left( \frac{R_{\text{NTC}}(T)}{R_{25}} \right)} + \frac{1}{25} \]

where:
- T is the temperature of the IGBT module
- \( R_{\text{NTC}}(T) \) is the NTC resistance at temperature T calculated from the voltage drop across the NTC
- \( R_{25} \) is the NTC resistance at 25°C available from the IGBT module datasheet
- B(25/50) is the B-constant of the NTC resistor available in the module datasheet
The NTC resistance is 5 kΩ at 25°C. The input impedance of AMC1306E25 is 22 kΩ, which is in parallel with the NTC resistance. This alters the voltage divider scaling ratio. The input bias current of the AMC1306 also flows through the NTC resistor adding to the error. For good temperature measurement accuracy that is cost effective, use a voltage follower buffer like the TLV521 as shown in Figure 13 to mitigate these error sources. R90, R91, and R92 are used to level shift the negative input to 0.250 V. This level shifting allows the use of the complete input range of the AMC1306. This TI Design does not use level shifting, so R90 is DNP and R91 is 0 Ω. Provision is given for the differential input filter using R93, R92, and C92. 22-Ω termination resistors are used on the data and clock lines for minimizing reflections.

3.5 Primary-Side 3.3-V Power Supply

The primary side of the board is provided with a 5-V input through terminal block J2 as shown in Figure 14. D1 is a Schottky diode for reverse polarity input protection. C5 is the input bulk capacitor and C14 is for noise decoupling. A LDO TLV1117-33 is used to generate 3.3 V from the input supply. A 100-µF bulk capacitor and 0.1-µF noise decoupling capacitor are used on the output. The maximum output current required from the LDO is 40 mA calculated from Table 3. The maximum power dissipation is 68 mW, which leads to a maximum junction temperature of 57.6°C for 55°C ambient.

![Figure 14. Schematic of Primary-Side 3.3-V Supply](image)

**Table 3. Current Requirement**

<table>
<thead>
<tr>
<th>DEVICE</th>
<th>NUMBER OF DEVICES</th>
<th>MAXIMUM CURRENT REQUIREMENT</th>
</tr>
</thead>
<tbody>
<tr>
<td>AMC1306E25</td>
<td>4</td>
<td>5.5 mA × 4 = 22 mA</td>
</tr>
<tr>
<td>Gate driver</td>
<td>7</td>
<td>2.5 mA × 7 = 17.5 mA</td>
</tr>
</tbody>
</table>
### 3.6 Secondary-Side 3.3-V Power Supply

The secondary-side 3.3-V power supply powers the DC bus voltage sensor and the temperature sensor. The LDO TLV70433 is used to generate 3.3 V from the 15-V low-side gate driver power supply. 4.7-µF bulk capacitors are placed on both the input and output of the LDO for fast transient response. The maximum current output requirement is 17 mA and the power dissipation across the LDO is 0.1989 W, which leads to a maximum junction temperature of 97°C for 55°C ambient.

![Figure 15. Schematic of Secondary-Side 3.3-V Power Supply](image)

#### Table 4. Current Requirement

<table>
<thead>
<tr>
<th>DEVICE</th>
<th>NUMBER OF DEVICES</th>
<th>MAXIMUM CURRENT REQUIREMENT</th>
</tr>
</thead>
<tbody>
<tr>
<td>AMC1306E25</td>
<td>2</td>
<td>2 × 8.5 mA = 17 mA</td>
</tr>
<tr>
<td>TLV521</td>
<td>1</td>
<td>500 nA</td>
</tr>
<tr>
<td>NTC Shunt divider</td>
<td>1</td>
<td>3.3 / (160K) = 20.6 µA</td>
</tr>
</tbody>
</table>
4 Getting Started Hardware

4.1 PCB Overview

Figure 16 shows the top view of the PCB. The DC bus input connector J8 and the three-phase motor output connector J4 are indicated. Provision is given to add a connector J3 for connecting an external brake resistor to the DC bus. The primary-side 5-V power supply is connected to J2, and the secondary-side isolated 15-V power supply is connected to J7. J1 is a female 25-pin D-SUB connector for interfacing to the controller.

Figure 16. Top View of TIDA-00914 PCB
Figure 17 indicates the primary low-voltage side, the secondary high-voltage side, and the reinforced isolation barrier in between.

Figure 17. Primary Side, Secondary Side, and Isolation Barrier
Figure 18 shows the bottom view of the PCB. Provision is given for adding brake chopper IGBT Q1 and freewheeling diode D9. The pad of the IGBT module has to be connected to a heat sink. The thermal compound has to be used between the pad and the heat sink, and the module must be rigidly screwed to the heat sink as shown in Figure 19. Choose an appropriate heat sink based on the maximum continuous power to be dissipated.

**NOTE:** The heat sink shown in Figure 19 is not optimized and is for testing purposes only.
4.2 **Controller Interface Connector**

The Delfino control card is connected to J1 on the TIDA-00914 board through an adaptor PCB as shown in Figure 20. A ribbon cable is used to connect the two. The pin functions are described in Table 5.
### Table 5. Connector Pin Description

<table>
<thead>
<tr>
<th>PIN NUMBER</th>
<th>PIN NAME</th>
<th>I/O</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>5V0</td>
<td>Power</td>
<td>5-V input to the primary side of the power stage</td>
</tr>
<tr>
<td>2</td>
<td>PWM_U+</td>
<td>3.3-V input</td>
<td>Phase U low-side gate driver PWM input</td>
</tr>
<tr>
<td>3</td>
<td>PWM_UT+</td>
<td>3.3-V input</td>
<td>Phase U high-side gate driver PWM input</td>
</tr>
<tr>
<td>4</td>
<td>PWM_VB+</td>
<td>3.3-V input</td>
<td>Phase V low-side gate driver PWM input</td>
</tr>
<tr>
<td>5</td>
<td>PWM_VT+</td>
<td>3.3-V input</td>
<td>Phase V high-side gate driver PWM input</td>
</tr>
<tr>
<td>6</td>
<td>PWM_WB+</td>
<td>3.3-V input</td>
<td>Phase W low-side gate driver PWM input</td>
</tr>
<tr>
<td>7</td>
<td>PWM_WT+</td>
<td>3.3-V input</td>
<td>Phase W high-side gate driver PWM input</td>
</tr>
<tr>
<td>8</td>
<td>PWM_BRAKE+</td>
<td>3.3-V input</td>
<td>PWM input to brake IGBT gate driver</td>
</tr>
<tr>
<td>9</td>
<td>NC</td>
<td>NA</td>
<td>NA</td>
</tr>
<tr>
<td>10</td>
<td>MDATA_U</td>
<td>3.3-V output</td>
<td>U phase current measurement data from ΔΣ modulator</td>
</tr>
<tr>
<td>11</td>
<td>NC</td>
<td>NA</td>
<td>NA</td>
</tr>
<tr>
<td>12</td>
<td>MDATA_W</td>
<td>3.3-V output</td>
<td>W phase current measurement data from ΔΣ modulator</td>
</tr>
<tr>
<td>13</td>
<td>5V0</td>
<td>Power</td>
<td>5-V input to the primary side of the power stage</td>
</tr>
<tr>
<td>14</td>
<td>GND</td>
<td>Power</td>
<td>Primary-side ground</td>
</tr>
<tr>
<td>15</td>
<td>GND</td>
<td>Power</td>
<td>Primary-side ground</td>
</tr>
<tr>
<td>16</td>
<td>GND</td>
<td>Power</td>
<td>Primary-side ground</td>
</tr>
<tr>
<td>17</td>
<td>GND</td>
<td>Power</td>
<td>Primary-side ground</td>
</tr>
<tr>
<td>18</td>
<td>GND</td>
<td>Power</td>
<td>Primary-side ground</td>
</tr>
<tr>
<td>19</td>
<td>GND</td>
<td>Power</td>
<td>Primary-side ground</td>
</tr>
<tr>
<td>20</td>
<td>GND</td>
<td>Power</td>
<td>Primary-side ground</td>
</tr>
<tr>
<td>21</td>
<td>NC</td>
<td>NA</td>
<td>NA</td>
</tr>
<tr>
<td>22</td>
<td>CLK</td>
<td>3.3-V input</td>
<td>Clock input to TIDA-00914 from the control card</td>
</tr>
<tr>
<td>23</td>
<td>MDATA_VDC</td>
<td>3.3-V output</td>
<td>DC bus voltage measurement data from ΔΣ modulator</td>
</tr>
<tr>
<td>24</td>
<td>MDATA_TMP</td>
<td>3.3-V output</td>
<td>Temperature measurement data from ΔΣ modulator</td>
</tr>
<tr>
<td>25</td>
<td>GND</td>
<td>Power</td>
<td>Primary-side ground</td>
</tr>
</tbody>
</table>
5 Testing and Results

The focus of the tests is to evaluate the functionality and performance of the shunt resistor-based reinforced isolated in-line phase current sensing using the AMC1306E25 $\Delta \Sigma$ modulator. Table 6 lists the key test equipment used.

Table 6. Key Test Equipment

<table>
<thead>
<tr>
<th>DESCRIPTION</th>
<th>PART NUMBER</th>
</tr>
</thead>
<tbody>
<tr>
<td>Oscilloscope</td>
<td>Tektronix MDO4104B-3</td>
</tr>
<tr>
<td>Single-ended probes</td>
<td>Tektronix TPP1000</td>
</tr>
<tr>
<td>Current probe</td>
<td>Keysight N2781B</td>
</tr>
<tr>
<td>Current probe amplifier</td>
<td>Agilent N2779A</td>
</tr>
<tr>
<td>Logic analyzer probes</td>
<td>Tektronix P6616</td>
</tr>
<tr>
<td>AC current standard</td>
<td>Yokogawa 2558A</td>
</tr>
<tr>
<td>Signal generator</td>
<td>Agilent 33220A</td>
</tr>
<tr>
<td>Multimeter</td>
<td>Keithley 2002, Fluke 87V</td>
</tr>
<tr>
<td>Power supply</td>
<td>Keithley 2230G-30-1</td>
</tr>
<tr>
<td>AC induction motor</td>
<td>3.7 kW, 1460 rpm (0.5 to 100 Hz), $415 V_{\text{RMS}} \pm 10%$, $\eta = 83 %$, $\cos \phi = 0.74$, $8.4 A_{\text{MAX}}$</td>
</tr>
<tr>
<td>High-voltage power supply</td>
<td>Agilent N5772A</td>
</tr>
</tbody>
</table>
5.1 Software

This TI Design is tested using software modified from the application report Sensorless Field Oriented Control of 3-Phase Permanent Magnet Synchronous Motors Using TMS320F2833x [3]. The incremental build level 2 shown in Figure 21 is modified. A switch is added to connect either the OUT signal coming from the RG MACRO or the angle variable to the sine cos block. Connecting OUT enables the design to pump sinusoidal current into the motor. Connecting the angle variable, which is made zero, enables driving DC current into the motor. The default ADC MACRO is used for reading data from a SAR ADC and is not suitable for ΔΣ modulators. This MACRO has been replaced by code for decoding the Manchester encoded data coming from the ΣΔ modulators and decimate the bit stream.

![Figure 21. PWM Control and Current Sense Software](image-url)
5.2 Detection of High-Side Power Loss in AMC1306E25

If the high-side power supply is missing, the output of the ΔΣ modulators is no longer valid. This causes loss of phase current feedback, resulting in system malfunction. The controller needs an indication that the high-side power is missing to take an appropriate action. This is done by the fail safe output feature of the AMC1306, as shown in Figure 22.

![Figure 22. Loss of High-Side Power Detection](image)

- Blue waveform: Secondary side AVDD
- Pink waveform: Current through phase U shunt resistor
- Digital channel 8: Modulator data bit stream
- Digital channel 9: Modulator clock signal

When the AVDD signal is lost, the output data pin of the modulator D8 provides a steady stream of logic 0's. In this case, it outputs the clock signal as the data is Manchester encoded. Note that for this test, current is pumped into the shunt resistor with an AC current standard equipment. No motor is connected to the inverter.

![Figure 23. Loss of High-Side Power Detection, Zoomed in](image)
5.3 Detection of Input Greater Than Full-Scale Input

When the phase current exceeds the maximum measurement range (that is, $V_{\text{IN}} \geq V_{\text{CLIPPING}} = \pm 0.320$ V), the modulator outputs a steady stream of logic 1’s or 0’s depending on the polarity of the current being measured. In order to differentiate from the loss of AVDD condition mentioned in Section 5.2, the device generates a toggle bit every 128 bits.

- Pink waveform: Current through phase U shunt resistor
- Digital channel 8: Modulator data bit stream
- Digital channel 9: Modulator clock signal

![Diagram of Negative Overrange Detection With Manchester Encoded Data](image)

**Figure 24. Negative Overrange Detection With Manchester Encoded Data**

![Diagram of Bit Sequence Immediately Before Overrange Detected](image)

**Figure 25. Bit Sequence Immediately Before Overrange Detected (Negative Overrange Detection With Manchester Encoded Data, Zoomed)**
Due to test setup limitations in reaching a current to exceed the maximum measurement range, the tests in this section use a 5-mΩ shunt resistor instead of a 4-mΩ shunt resistor used for rest of the test. Figure 24 shows the instant at which overrange is detected. Figure 25 is the zoomed-in version of Figure 24, showing that before overrange there is valid data shown by data bit toggle after 5.9 µs. After this bit, there are bit toggles every 128 bits, indicating that the AMC input has exceeded the maximum measurable input. Figure 26 shows the detection of overrange at –62 A (–62 A × 5 mΩ = –0.31 V). The bit toggle at every 128-bit interval (1/20 MHz × 128 = 6.4 µs) is shown. Figure 27 shows the detection of overrange at 64 A (64 A × 5 mΩ = 0.32 V). The bit toggle at every 128-bit interval (1/20 MHz × 128 = 6.4 µs) is shown.

**NOTE:** Because the data is Manchester encoded, a constant logic one or zero translates to look like a clock signal. A logic bit toggle is when there is a 180° phase shift in the data signal.
Short-Circuit Response Time

Fast short-circuit protection is very important to protect both the motor and inverter power stage from damage. On short circuits, the IGBTs have to be switched off within 4 µs. Newer generation IGBTs switch faster but usually trade off with robustness against short circuit. These IGBTs have to be switched off in less than 2 µs. The response time to short circuit depends on the order of the SINC filter used and the OSR, as shown in Equation 7.

\[
\text{Response time, } t_r = n \times \frac{\text{OSR}}{\text{fs}}
\]

where:
- \( n \) is the order of the SINC filter
- \( \text{OSR} \) is the oversampling ratio of the SDFM
- \( \text{fs} \) is the modulator clock frequency

The short-circuit response time is captured for three different combinations of SINC filter order and OSR:
- SINC 1, 24 OSR
- SINC 2, 12 OSR
- SINC 3, 8 OSR

Each of the three combinations have the same theoretical response time of 1.2 µs. For the test setup, the shunt resistor is unpopulated and the AMC inputs are instead connected to a function generator. The function generator applies a positive and negative step input. The output of the SDFM comparator module is routed to a GPIO. The response time is equal to the time delay between the rising edges of the step input and the GPIO signal. An additional delay of \( \approx 200 \) to 300 ns is captured in the test results, which is due to the time required to execute the instructions needed to toggle the GPIO pin. The short-circuit detection threshold has been set to \( \pm 40 \) A. The threshold values required to be set in software for the different filter combinations are shown in Table 7.

<table>
<thead>
<tr>
<th>FILTER ORDER</th>
<th>OSR</th>
<th>PEAK DATA VALUE</th>
<th>DATA VALUE FOR 0 A</th>
<th>DATA VALUE FOR 40 A</th>
<th>DATA VALUE FOR –40 A</th>
<th>CURRENT MEASUREMENT RESOLUTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>SINC 1</td>
<td>24</td>
<td>24</td>
<td>12</td>
<td>18</td>
<td>6</td>
<td>6.6600 A</td>
</tr>
<tr>
<td>SINC 2</td>
<td>12</td>
<td>144</td>
<td>72</td>
<td>108</td>
<td>36</td>
<td>1.1100 A</td>
</tr>
<tr>
<td>SINC 3</td>
<td>8</td>
<td>512</td>
<td>256</td>
<td>384</td>
<td>128</td>
<td>0.3125 A</td>
</tr>
</tbody>
</table>

Table 7 shows that the SINC 3 filter with OSR 8 has the best current measurement resolution for the same response time.

Figure 28, Figure 29, and Figure 30 show the optimum response time for positive step input. Figure 31, Figure 32, and Figure 33 show the optimum response time for negative step input.

Figure 34, Figure 35, and Figure 36 show the uncertainty in response time. This uncertainty is captured by putting the scope in high-persistence mode. This TI Design uses the C2000™ Delfino. The SINC filters implemented in the Delfino use the hardware-optimized Hogenauer structure to take advantage of decimation. This structure provides benefits in reducing the number of clock cycles needed to implement a SINC filter, resulting in a significant power saving. The disadvantage being the output of the filter is clocked at the modulator clock frequency divided by the OSR. Any event occurring between adjacent OSR/fs transitions will be reflected at the next transition only. This puts a maximum jitter uncertainty of OSR/fs.

As can be seen from the following figures, the higher the OSR, the higher the jitter. Using a SINC 3 filter with 8 OSR provides the least jitter as well as the best current measurement resolution. If the filter is implemented in an FPGA where concurrent processing is done and the SINC filter demodulation modules are clocked at the full modulator clock frequency, then the best response time shown in Table 7 is always achieved.
5.5 **Current Sense Measurement Accuracy**

Figure 37 shows the test setup for checking the performance of the current measurement. A 4-mΩ shunt resistor is used to measure the phase current. The voltage drop across the shunt resistor is measured by the AMC1306 ΔΣ modulator. The modulator output bit stream is channeled into the control card. The control card is configured to implement SINC filters of different orders and OSRs. The reading from the control card is compared with the actual phase current measured with a multimeter to determine the measurement error. The center of the SINC filter window is synchronized to the center of the PWM pulse as shown in Figure 38. This ensures that no switching noise gets into the SINC filter window and the measured current is the average current. For characterizing the current measurement performance, a DC current has been pumped into the motor by making the input to the sin/cos block zero as mentioned in Section 5.1. Figure 39 shows the transfer function of the current sense circuit.
Figure 37. Test Setup

Figure 38. Sample Window
Figure 39. Transfer Function of Current Sensor

Figure 40 shows the absolute error and calibrated absolute error in amperes. The X-axis indicates the phase current and the Y-axis the current measurement error. The test has been done up to 10 A due to test setup limitations. A SINC 3 filter with 256 OSR is used, the modulator clock frequency is set to 20 MHz, and the PWM switching frequency is set to 4 kHz.

Figure 40. Absolute Error in Amperes
Figure 41 shows the % FSR error and the % calibrated FSR.

![Graph showing FSR error as a percentage of full-scale range.](image)

**Figure 41. Error as Percentage of Full-Scale Range**

Figure 42 shows the absolute calibrated error at different OSR values. The measurement error with a SINC 3 filter and OSRs of 256, 128, and 64 are plotted at 25 °C.

![Graph showing error versus OSR.](image)

**Figure 42. Error Versus OSR**
Figure 43 shows the absolute calibrated error at different temperatures. A SINC 3 filter with 256 OSR is used, and the measurements are done at 0°C, 25°C, and 55°C.

Figure 43. Error Versus Temperature
6 Design Files

6.1 Schematics
To download the schematics, see the design files at TIDA-00914.

6.2 Bill of Materials
To download the bill of materials (BOM), see the design files at TIDA-00914.

6.3 PCB Layout Recommendations
Figure 44 shows the isolation barrier and ground split. The hot-side (high-voltage power side) and the cold-side (low-voltage controller side) copper tracks are separated from each other by a reinforced isolation barrier. The wide body package of the gate driver and \( \Delta \Sigma \) modulators are placed across the isolation barrier. A copper-to-copper creepage spacing of 8.89 mm is maintained between the hot and cold sides.

The low-side gate driver grounds and DC bus negative are common. To avoid noise due to switching currents in the DC bus negative from interfering with the gate driver operation, a split is done in the ground plane and they are connected together at a single point as shown in Figure 44.
Figure 44. Reinforced Isolation Barrier and Ground Splits
The shunt resistance of 4 mΩ is in the same range as that of the stray parasitic trace resistances. For accurate shunt-based current sensing, it is important to sense the exact voltage across the shunt resistor only and avoid measuring the drop across the trace and contact parasitic resistance. This is done by implementing a Kelvin connection as shown in Figure 45. Differential routing is done from the shunt resistor to the ΔΣ modulator. Any noise is common to both the traces and gets cancelled off in the differential input stage of the modulator.

![Figure 45. Shunt Resistor Connection to ΔΣ Modulator](image)

Figure 46 shows the layout of the ΔΣ modulator circuit. R47 and R46 are 22-Ω termination resistors placed close to the clock and data signal pins. C62 and C66 are primary-side noise decoupling capacitors that have to be placed close to the power pin. R79, R80, and C84 form an external differential filter, which is placed symmetrically. C21 is the input capacitor for LDO U22, which converts 15 V to 5 V. C89 and C85 are secondary-side decoupling capacitors.

![Figure 46. ΔΣ Modulator](image)
Figure 47 shows the DC bus voltage sense circuit. The high-impedance resistor divider network is connected across the pins of the high-voltage DC-link film capacitor C111. The attenuated voltage is sensed by ΔΣ modulator U12. It is important to sense the voltage across the film capacitor for low-noise measurement.

6.3.1 Layout Prints
To download the layer plots, see the design files at TIDA-00914.

6.4 Altium Project
To download the Altium project files, see the design files at TIDA-00914.

6.5 Gerber Files
To download the Gerber files, see the design files at TIDA-00914.

6.6 Assembly Drawings
To download the assembly drawings, see the design files at TIDA-00914.

7 Related Documentation
1. Texas Instruments, Isolated Current Shunt and Voltage Measurement Kit, TIDA-00171 reference design guide
3. Texas Instruments, Sensorless Field Oriented Control of 3-Phase Permanent Magnet Synchronous Motors Using TMS320F2833x, application report
4. Texas Instruments, Wide-Input Isolated IGBT Gate-Drive Fly-Buck™ Power Supply for Three-Phase Inverters, TIDA-00199 reference design guide
6. Texas Instruments, Basic Isolated Three-Phase Compact Power Stage Reference Design for Industrial Drives, TIDA-01420 reference design guide

7.1 Trademarks
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8 Terminology

IGBT—Insulated gate bipolar transistor
ACIM—Alternating current induction motor
VFD—Variable frequency drive
PWM—Pulse width modulation
UVLO—Undervoltage lockout
SDFM—Sigma-delta filter module
DNP—Do not populate
OSR—Oversampling ratio
FSR—Full-scale range

9 About the Author

PAWAN NAYAK is a systems engineer at Texas Instruments, where he is responsible for developing reference design solutions for the Motor Drive segment within Industrial Systems.

9.1 Recognition

Pawan Nayak would like to recognize the excellent contributions from MARTIN STAEBLER, N. NAVANEETH KUMAR, and NELSON ALEXANDER during the design, test, and documentation phases of the TIDA-00914 device.
# Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<table>
<thead>
<tr>
<th>Changes from Original (May 2017) to A Revision</th>
<th>Page</th>
</tr>
</thead>
<tbody>
<tr>
<td>• Changed UCC5390SCDWV to UCC5390ECDWV in Resources section</td>
<td>1</td>
</tr>
<tr>
<td>• Changed TIDA-00914 block diagram</td>
<td>1</td>
</tr>
<tr>
<td>• Added UCC5310MCDWV block diagram</td>
<td>5</td>
</tr>
<tr>
<td>• Added UCC5310MCDWV to Highlighted Products</td>
<td>9</td>
</tr>
<tr>
<td>• Added TIDA-01420 Design Guide to Related Documentation section</td>
<td>36</td>
</tr>
</tbody>
</table>
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